

Electronic Patent Application Fee Transmittal

Application Number:	10595303
Filing Date:	19-May-2006
Title of Invention:	Method and Device For Secure, Insulated and Electrically Conductive Assembling Of Treated Semiconductor Wafers
First Named Inventor/Applicant Name:	Roy Knechtel
Filer:	Yisun Song/Robin Taylor
Attorney Docket Number:	60291.000048

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				
Extension - 1 month with \$0 paid	1251	1	120	120

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				120